EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	30	(substrate with (fold$3 bend$3 bent wrap$4) with (chip ic semiconductor component) and (tool folder jig holder guide fixture) with (fold$3 bend$3 bent wrap$4)).clm.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/22 15:34
L2	107	"29"/$.ccls. and (board substrate) with (fold$3 bend$3 bent wrap$4) with (chip microelectronic ic semiconductor component) and (tool folder jig holder guide fixture) with (fold$3 bend$3 bent wrap$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/22 15:38
L3	68	"361"/$.ccls. and (board substrate) with (fold$3 bend$3 bent wrap$4) with (chip microelectronic ic semiconductor component) and (tool folder jig holder guide fixture) with (fold$3 bend$3 bent wrap$4) not 2	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/22 15:40
L4	9	"174"/$.ccls. and (board substrate) with (fold$3 bend$3 bent wrap$4) with (chip microelectronic ic semiconductor component) and (tool folder jig holder guide fixture) with (fold$3 bend$3 bent wrap$4) not 2 not 3	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/22 15:41
L5	64	"438"/$.ccls. and (board substrate) with (fold$3 bend$3 bent wrap$4) with (chip microelectronic ic semiconductor component) and (tool folder jig holder guide fixture) with (fold$3 bend$3 bent wrap$4) not 2 not 3	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/22 15:45
L6	83	"257"/$.ccls. and (board substrate) with (fold$3 bend$3 bent wrap$4) with (chip microelectronic ic semiconductor component) and (tool folder jig holder guide fixture) with (fold$3 bend$3 bent wrap$4) not 2 not 3 not 5	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/22 15:46
L7	19	("4677458").URPN.	USPAT	OR	ON	2006/08/22 15:48
S3	2	bang.in. and fold$3 with substrate.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/09 15:24
S25	61	("3766439").URPN.	USPAT	OR	ON	2006/08/09 14:50

S26	14	("20010018225" | "20020180022" | "20030067064" | "20040021212" | "20040115866" | "20040238936" | "20050041403" | "3766439" | "5386341" | "5534727" | "5776797" | "5914859" | "6208521" | "6559522").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/09 14:51
S27	11	bang.in. and substrate.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/08/09 15:24
S28	3078	substrate with (fold$3 bend$3 bent wrap$4) with (chip ic semiconductor component)	USPAT; EPO; JPO	OR	ON	2006/08/09 15:27
S29	253	substrate with (fold$3 bend$3 bent wrap$4) with (chip ic semiconductor component) same (tool die guide)	USPAT; EPO; JPO	OR	ON	2006/08/09 15:59
S30	221	substrate with (fold$3 bend$3 bent wrap$4) with (chip ic semiconductor component) and (tool folder jig holder guide) with (fold$3 bend$3 bent wrap$4)	USPAT; EPO; JPO	OR	ON	2006/08/09 16:00
S31	130	substrate with (fold$3 bend$3 bent wrap$4) with (chip ic semiconductor component) and (tool folder jig holder guide) with (fold$3 bend$3 bent wrap$4) not S29	USPAT; EPO; JPO	OR	ON	2006/08/09 16:01